

## ABSTRACT OF THE DISCLOSURE

Methods of assembling an electronic package including forming a housing with a first bond pad on a top surface of a bond shelf, forming a conductive strip along a side surface or edge of the bond shelf, and removing a portion of the conductive strip to form a pair of separate conductive strips. The conductive strip may be formed by plating a conductive material onto the bond shelf into unmasked areas thereof. The conductive strip may include a portion that extends around from the side surface to the top surface of the bond shelf to form a bond pad or couple to a bond pad on the top surface. The extended portion may also anchor the conductive strip and the separate conductive strips to the housing and reduce the likelihood of delamination during removal of the portion of the conductive strip to form the separate conductive strips.